



RESPONSE UNDER 37 C.F.R. § 1.116

EXPEDITED PROCEDURE – Art Unit 3723

Attorney Docket No. 108298515US2

Express Mail Label EV253247797US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Whonchee Lee *et al.*

APPLICATION No.: 09/887,767

FILED: June 21, 2001

FOR: **MICROELECTRONIC SUBSTRATE
HAVING CONDUCTIVE MATERIAL WITH
BLUNT CORNERED APERTURES, AND
ASSOCIATED METHODS FOR REMOVING
CONDUCTIVE MATERIAL**

EXAMINER: Alvin J. Grant

ART UNIT: 3723

CONF. No: 9072

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FEB 20 2003

TECHNOLOGY CENTER R3700

Amendment Under 37 C.F.R. § 1.116

Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The present communication responds to the Final Office Action dated November 6, 2002, in the above-identified application. Please amend the application as follows. The attached Appendix presents a marked-up version of the changes made to the claims by the current amendment.

In the Claims:

Please amend claims 1, 20 and 41 as follows. Please cancel claims 19, 36 and 52-71. Following is a complete listing of the claims pending in the application, as amended:

1. (Amended) A method for processing a microelectronic substrate, comprising:

disposing an electrolytic fluid adjacent to a conductive material of the microelectronic substrate, the conductive material having a first surface in a first plane